



P-Channel 60 V (D-S) MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	-60				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -10 V	0.0195				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5 \text{ V}$	0.0250				
Q _g typ. (nC)	76				
I _D (A) ^a	-53				
Configuration	Single				

FEATURES

- TrenchFET® power MOSFET
- 100 % UIS tested

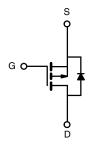




RoHS COMPLIANT

APPLICATIONS

Load switch



P-Channel MOSFET

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	SUP53P06-20-E3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless parameter		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	-60	.,	
Gate-source voltage		V _{GS}	± 20	V	
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		-53 ^a		
	T _C = 70 °C		-46.8		
	T _A = 25 °C	I _D	9.2 b		
	T _A = 70 °C		-8.1 b	A	
Pulsed drain current		I _{DM}	-150		
Avalanche current pulse	L = 0.1 mH	I _{AS}	-45		
Single pulse avalanche energy	L = 0.1 mn	E _{AS}	101	mJ	
Continuous source-drain diode current	T _C = 25 °C		69 ^a	^	
	T _A = 25 °C	I _S	2.1 ^b	A	
Maximum power dissipation	T _C = 25 °C		104.2 ^a		
	T _C = 70 °C		66.7 ^a	10/	
	T _A = 25 °C	P _D	3.1 ^b	W	
	T _A = 70 °C		2 b		
Operating junction and storage temperature range		T _J , T _{stq}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient ^b	Steady state	R _{thJA}	33	40	°C/W	
Maximum junction-to-case	Steady state	R_{thJC}	0.98	1.2	C/VV	

Notes

a. Based on $T_C = 25 \, ^{\circ}C$

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b. Surface mounted on 1" x 1" FR4 board

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I 050 A	-	68	-	mV/°C	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	=	-5.2	-	IIIV/ C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-1	-	-3	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
7 de alle a de la constante de la const		V _{DS} = -60 V, V _{GS} = 0 V	-	-	-1		
Zero gate voltage drain current	I _{DSS}	V _{DS} = -60 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-10	μA	
On-state drain current ^a	I _{D(on)}	V _{DS} = -5 V, V _{GS} = -10 V	-120	-	-	Α	
Drain accuracy on state registeres 3	В	$V_{GS} = -10 \text{ V}, I_D = -30 \text{ A}$	-	0.0160	0.0195		
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -20 \text{ A}$	-	0.0200	0.0250	Ω	
Forward transconductance a	9 _{fs}	V _{DS} = -15 V, I _D = -50 A	20	-	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	3500	-	pF	
Output capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	390	-		
Reverse transfer capacitance	C _{rss}		=	290	-		
Total gata abayes	0	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -55 \text{ A}$	-	76	115	nC	
Total gate charge	Qg		-	38	60		
Gate-source charge	Q _{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -55 \text{ A}$	-	16	-		
Gate-drain charge	Q _{gd}		-	19	-		
Gate resistance	R _g	f = 1 MHz	-	5.2	-	Ω	
Turn-on delay time	t _{d(on)}		-	10	15		
Rise time	t _r	V_{DD} = -2 V, R_L = 2 Ω	-	7	15		
Turn-off delay time	t _{d(off)}	$I_D\cong$ -10 A, $V_{GEN}=$ -10 V, $R_g=$ 1 Ω	-	70	110	ns	
Fall time	t _f		-	40	60		
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	-69	_	
Pulse diode forward current ^a	I _{SM}	И		-	-150	A	
Body diode voltage	V _{SD}	I _S = -30 A	-	-1	-1.5	V	
Body diode reverse recovery time	t _{rr}		-	45	68	ns	
Body diode reverse recovery charge	Q _{rr}	L 50 A di/dt 100 A/v.c T 05 °C	-	59	120	nC	
Reverse recovery fall time	ta	$I_F = -50 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	-	29	-		
Reverse recovery rise time	t _b		-	16	-	ns	

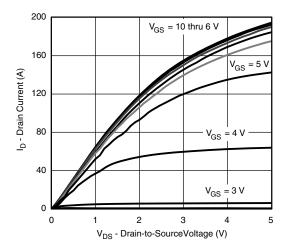
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing

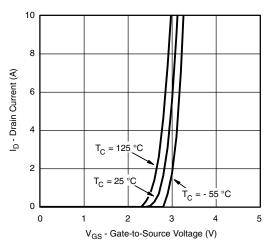
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



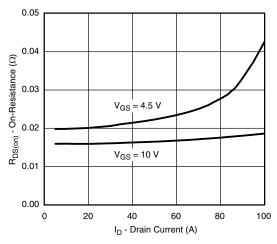
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



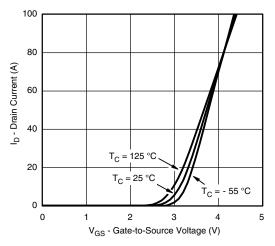
Output Characteristics



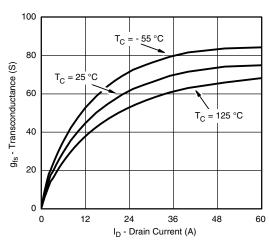
Transfer Characteristics



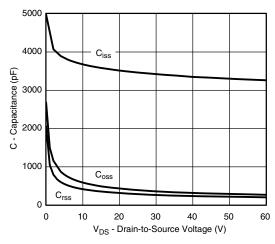
On-Resistance vs. Drain Current



Transfer Characteristics



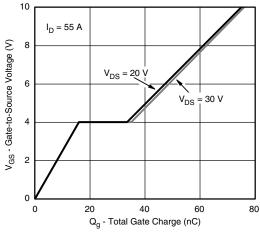
Transconductance



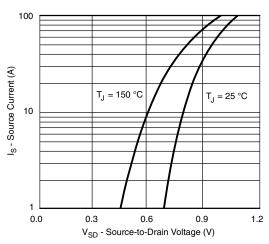
Capacitance



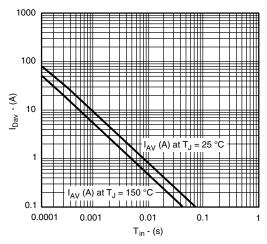
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



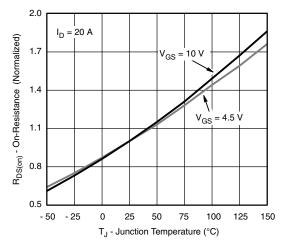
Gate Charge



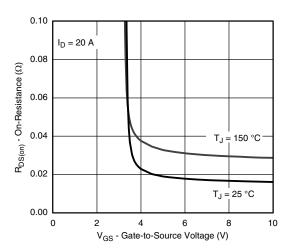
Source-Drain Diode Forward Voltage



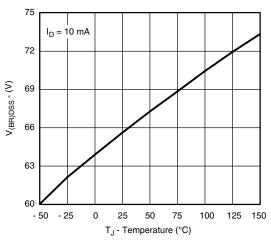
Single Pulse Avalanche Current Capability vs. Time



On-Resistance vs. Gate-to-Source Voltage



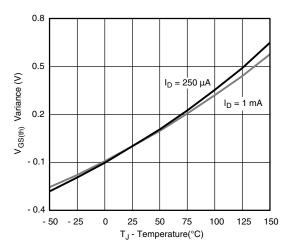
On-Resistance vs. Gate-to-Source Voltage



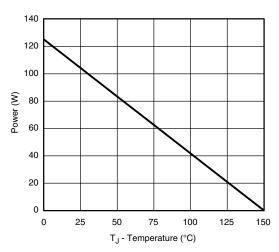
Drain-Source Breakdown Voltage vs. Junction Temperature



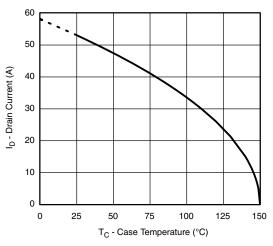
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



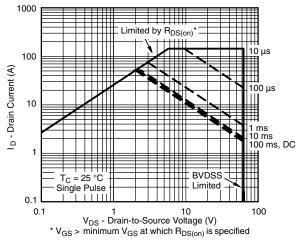
Threshold Voltage



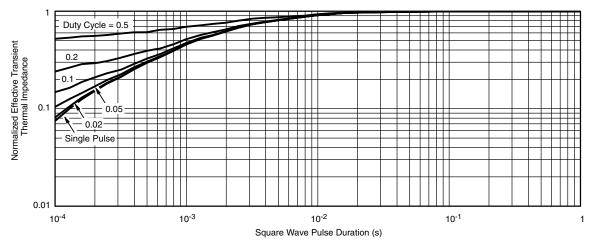
Power Derating, Junction-to-Case



Max. Drain Current vs. Case Temperature



Safe Operating Area, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Case

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TO-220AB



	D2

	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

Note

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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